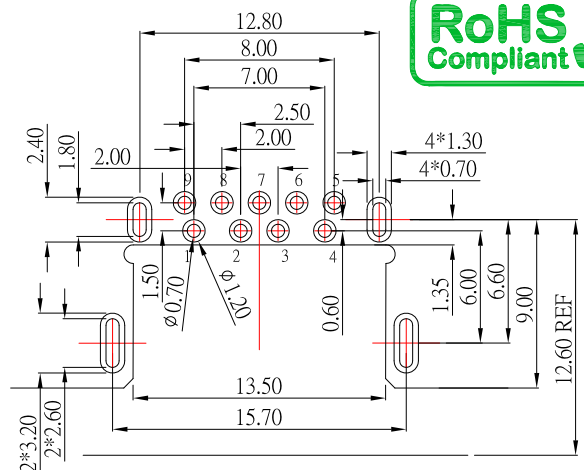
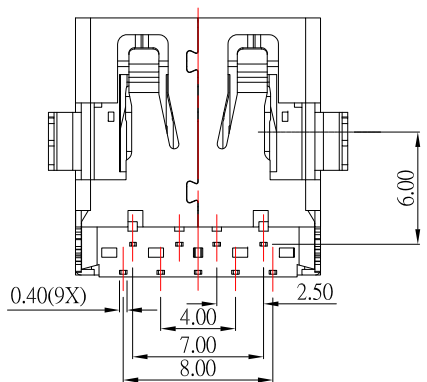
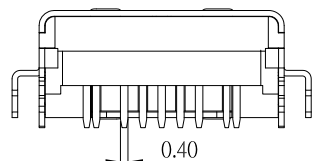
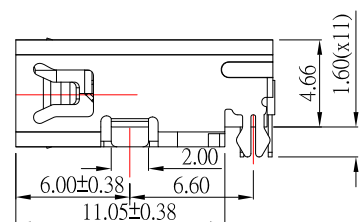
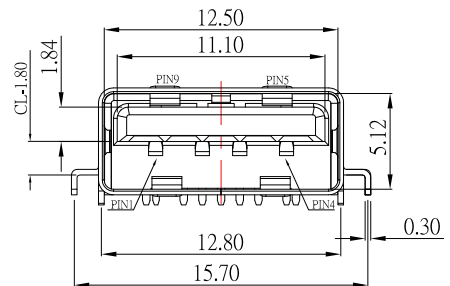
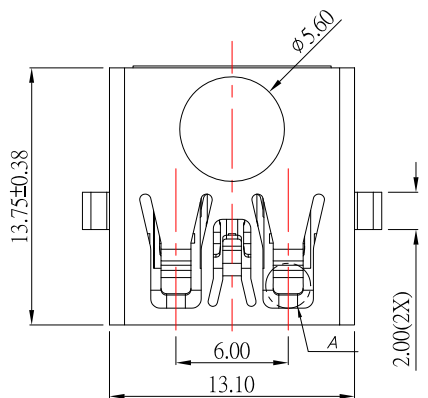




SUA-110E18-30x-S242

鍍層厚度：

Blank : 1u"
2 : 15u"
3 : 30u"



RECOMMENDED PCB LAYOUT

NOTE:

- 1.MATERIAL:
 - 1.1 Housing: LCP
 - 1.2 Contact: Phosphor Bronze
 - 1.3 Shell: SUS201
- 2.Finish:
 - 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
 - 2.2 Shell: Nickel under Plated surface layer
- 3.SPECIFICATION:
 - 3.1 Rate: 30V DC , 1.5 A
 - 3.2 Insulator Resistance:100MΩ Min
 - 3.3 Dielectric Strength: 500V AC
 - 3.4 Contact Resistance: 30mΩ Max
 - 3.5 Operation Temperature: -55°C ~ +85°C

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
 Up to 5 ±0.2
 Above 5 ~ 15 ±0.3
 Above 15 ~ 30 ±0.4
 Above 30 ~ 50 ±0.5
 Angle ±0.3

3RD. ANGEL'S



UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	03/29/22		MODLE	USB AF 3.0 SMT 沉板板上H4.46mm L13.75 無捲邊
CHECKED BY:	DATE	SCALE	DWG NO.	SUA-110E18-30x-S242
Jacky Chen	03/29/22	1 : 1	PART NO.	SUA-110E18-30x-S242
APPROVED BY:	DATE	SHEET NO.		SIZE
Tony Kao	03/29/22	1 of 1		A4
				VER
				R2

ITEM NO.	DESCRIPTION	DRAWN	DATE
2	新增尺寸和更新樣式	Jack	032922
1	更新樣式	Jack	032522